

Datasheet revision 1.0

www.chipquik.com

# Chip Quik Removal Alloy (16ft. In 30-6.5in. Lengths) lead-free

Product Highlights

Easily remove SMD parts with Chip Quik® removal alloy Reduce heat and reduce damage to circuit boards and SMD parts during removal Use with SMD291 flux RoHS II and REACH compliant

Specifications

Alloy: Melting Point: Chip Quik® lead-free 79-91°C (174-195°F)

| Chip Quik® Instructions |   |   |
|-------------------------|---|---|
|                         | 1 | Apply Chip Quik flux to all leads of SMD with syringe or flux applicator.   |
|                         | 2 | Melt Chip Quik low temperature alloy uniformly on all pins of SMD.<br>Maintain alloy in molten state long enough for complete reflow. |
|                         | 3 | Lift chip from board with dental pick or vacuum pen.  |
|                         | 4 | Thoroughly clean site with swab dipped in flux while applying heat.<br>Clean thoroughly with alcohol pad.                             |

## SMD Removal

### (With solder iron or warm air bath)

- Apply flux to all leads.
- Melt CHIP QUIK® uniformly on all pins.
- Maintain alloy in molten state long enough to release chip.
- Lift chip from board with dental pick or vacuum pen.

# **CLEAN UP**

- While molten, use cotton swab and flux to move excess to an unused section of board.
- While applying heat, polish each pad with a swab and flux until thoroughly clean.
- At room temperature, clean residue with alcohol pad.
- You are now ready to install the new chip.

## 2.5 ft of Chip Quik® material, removes 1250 to 1500 SMD pins.

Conforms to the following Industry Standards: J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): RoHS 2 Directive 2011/65/EU: Yes